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January 2009

# FDD6776A / FDU6776A\_F071

# N-Channel PowerTrench® MOSFET 25 V, 7.5 m $\Omega$

#### **Features**

- Max  $r_{DS(on)} = 7.5 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$ ,  $I_D = 17.7 \text{ A}$
- Max  $r_{DS(on)} = 17.0 \text{m}\Omega$  at  $V_{GS} = 4.5 \text{ V}$ ,  $I_D = 13.2 \text{ A}$
- 100% UIL test
- RoHS Compliant

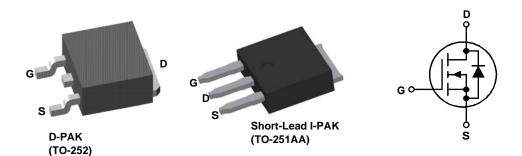


## **General Description**

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low  $r_{\mbox{\footnotesize{DS(on)}}}$  and fast switching speed.

# **Applications**

- Vcore DC-DC for Desktop Computers and Servers
- VRM for Intermediate Bus Architecture



# **MOSFET Maximum Ratings** $T_C = 25$ °C unless otherwise noted

Symbol	Parameter		Ratings	Units	
V <sub>DS</sub>	Drain to Source Voltage			25	V
V <sub>GS</sub>	Gate to Source Voltage			±20	V
I <sub>D</sub>	Drain Current -Continuous (Package limited)	T <sub>C</sub> = 25 °C		30	
	-Continuous (Silicon limited) T <sub>C</sub> :			54	^
	-Continuous	T <sub>A</sub> = 25 °C	(Note 1a)	17.7	— A
	-Pulsed			100	
E <sub>AS</sub>	Single Pulse Avalanche Energy		(Note 3)	32	mJ
D	Power Dissipation	T <sub>C</sub> = 25 °C		39	W
$P_{D}$	Power Dissipation	T <sub>A</sub> = 25 °C	(Note 1a)	3.7	VV
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature R	ange		-55 to +175	°C

#### **Thermal Characteristics**

F	$R_{\theta JC}$	Thermal Resistance, Junction to Case	3.8	°C/W
F	$R_{\thetaJA}$	Thermal Resistance, Junction to Ambient (Note 1a	40	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD6776A	FDD6776A	D-PAK (TO-252)	13 "	12 mm	2500 units
FDU6776A	FDU6776A_F071	TO-251AA	N/A(Tube)	N/A	75 units

# **Electrical Characteristics** $T_J = 25$ °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	25			V
$\frac{\Delta BV_{DS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, referenced to 25 °C		16		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA

#### **On Characteristics**

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.0	1.9	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, referenced to 25 °C		-6		mV/°C
		$V_{GS} = 10 \text{ V}, I_D = 17.7 \text{ A}$		5.8	7.5	
		$V_{GS}$ = 10 V, $I_D$ = 17.7 A Short-Lead I-PAK version		6.0	7.7	
r <sub>DS(on)</sub>	Static Drain to Source On Resistance	$V_{GS} = 4.5 \text{ V}, I_D = 13.2 \text{ A}$		12.6	17.0	mΩ
		$V_{GS}$ = 4.5 V, $I_D$ = 13.2 A Short-Lead I-PAK version		12.8	17.2	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 17.7 A, T <sub>J</sub> = 150 °C		8.8	11.4	
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = 5 \text{ V}, I_D = 17.7 \text{ A}$		84		S

### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	V 42 V V 0 V	1120	1490	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 13 V, V <sub>GS</sub> = 0 V, f = 1 MHz	238	320	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 1 1011 12	221	335	pF
$R_g$	Gate Resistance		0.9		Ω

# **Switching Characteristics**

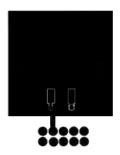
t <sub>d(on)</sub>	Turn-On Delay Time		8	16	ns
t <sub>r</sub>	Rise Time	$V_{DD} = 13 \text{ V}, I_{D} = 17.7 \text{ A},$	5	10	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$V_{GS} = 10 \text{ V}, R_{GEN} = 6 \Omega$	18	33	ns
t <sub>f</sub>	Fall Time		3	10	ns
$Q_q$	Total Gate Charge	V <sub>GS</sub> = 0 V to 10 V	20	29	nC
$Q_q$	Total Gate Charge	$V_{GS} = 0 \text{ V to 5 V}$ $V_{DD} = 13 \text{ V},$	12	17	nC
$Q_{gs}$	Gate to Source Charge	I <sub>D</sub> = 17.7 A	3.5		nC
$Q_{gd}$	Gate to Drain "Miller" Charge		4.9		nC

#### **Drain-Source Diode Characteristics**

V <sub>CD</sub> Source to Drain Diode Forward Voltage	Source to Drain Diade Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 3.1 \text{ A}$ (Not	e 2)	0.8	1.2	V
	$V_{GS} = 0 \text{ V}, I_S = 17.7 \text{ A}$ (Not	e 2)	0.9	1.3	V	
t <sub>rr</sub>	Reverse Recovery Time	-I <sub>F</sub> = 17.7 A, di/dt = 100 A/μs		17	31	ns
Q <sub>rr</sub>	Reverse Recovery Charge	$-1F = 17.7 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{S}$		5	10	nC

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1: R<sub>0JA</sub> is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R<sub>0JC</sub> is guaranteed by design while R<sub>0JA</sub> is determined by the user's board design.



a) 40 °C/W when mounted on a 1 in<sup>2</sup> pad of 2 oz copper



b) 96 °C/W when mounted on a minimum pad.

- 2: Pulse Test: Pulse Width < 300  $\mu$ s, Duty cycle < 2.0%. 3: E<sub>AS</sub> of 32 mJ is based on starting T<sub>J</sub> = 25 °C, L = 1 mH, I<sub>AS</sub> = 8 A, V<sub>DD</sub> = 23 V, V<sub>GS</sub> = 10 V. 100% test at L = 0.1 mH, I<sub>AS</sub> = 19 A.

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

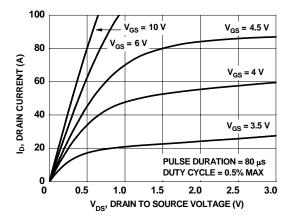


Figure 1. On-Region Characteristics

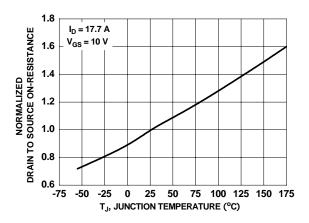


Figure 3. Normalized On-Resistance vs Junction Temperature

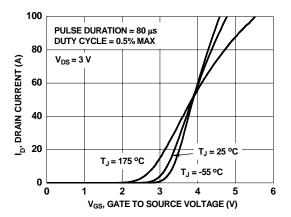


Figure 5. Transfer Characteristics

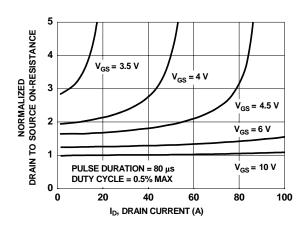


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

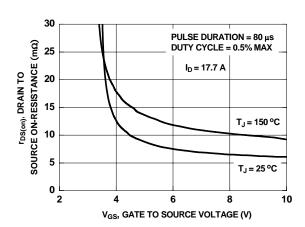


Figure 4. On-Resistance vs Gate to Source Voltage

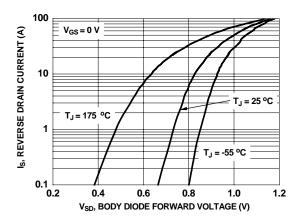


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

# **Typical Characteristics** $T_J = 25$ °C unless otherwise noted

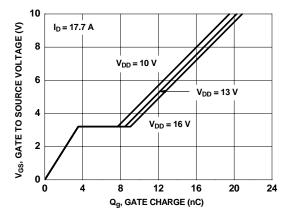


Figure 7. Gate Charge Characteristics

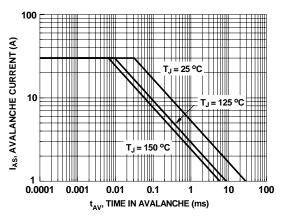


Figure 9. Unclamped Inductive Switching Capability

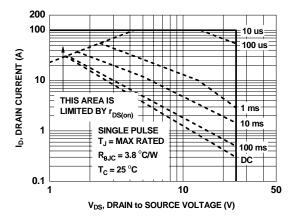


Figure 11. Forward Bias Safe Operating Area

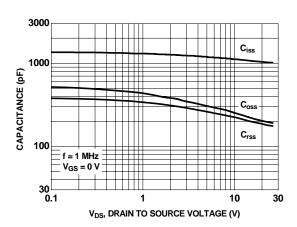


Figure 8. Capacitance vs Drain to Source Voltage

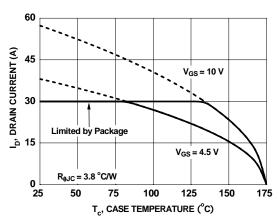


Figure 10. Maximum Continuous Drain Current vs Case Temperature

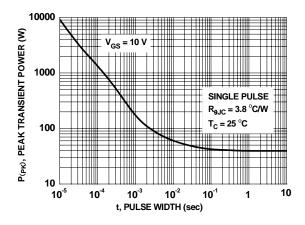


Figure 12. Single Pulse Maximum Power Dissipation

# Typical Characteristics T<sub>J</sub> = 25 °C unless otherwise noted

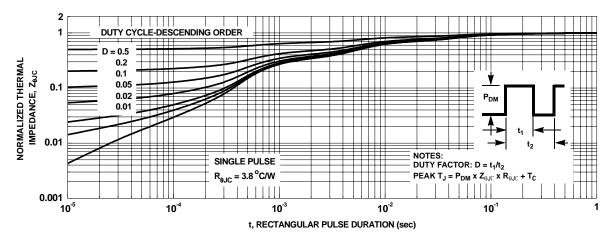


Figure 13. Transient Thermal Response Curve

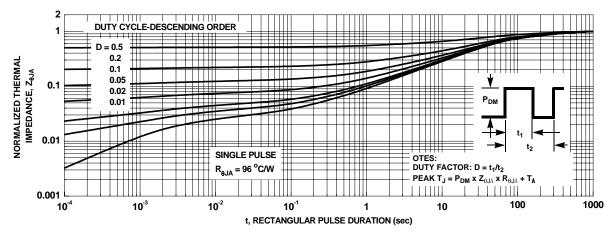


Figure 14. Transient Thermal Response Curve





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